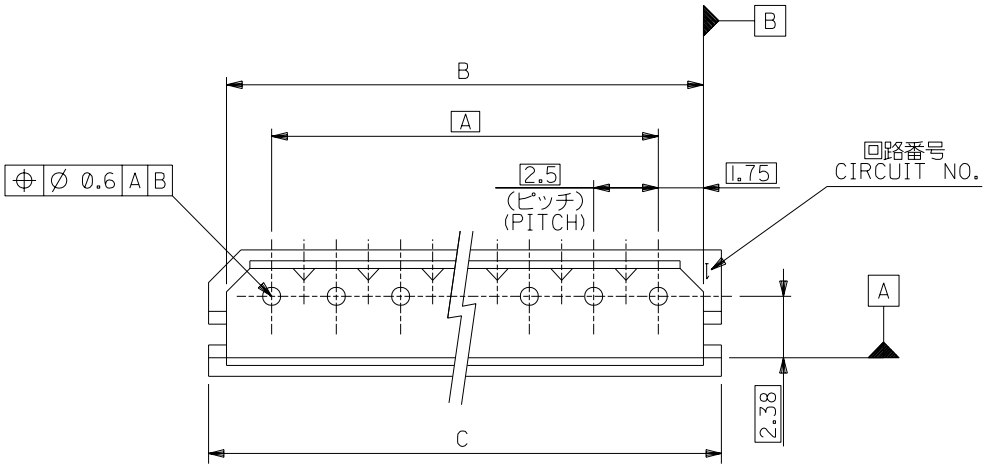
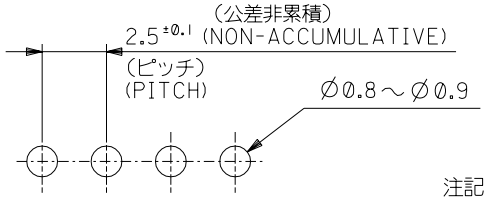


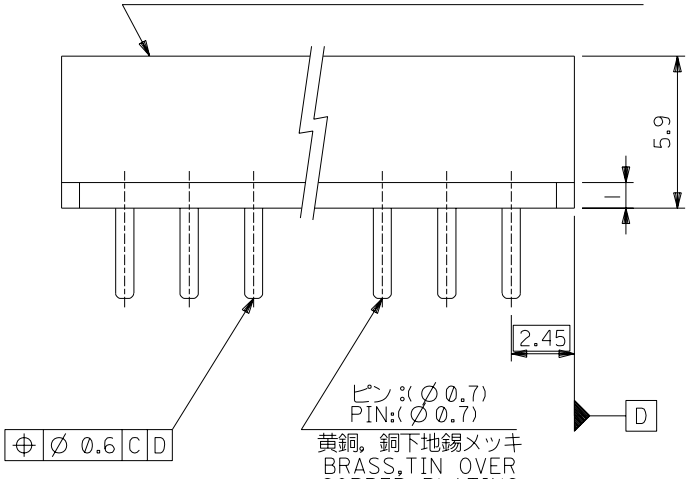


基板取付穴推奨寸法
RECOMMENDED P.C.BOARD HOLE DIM.

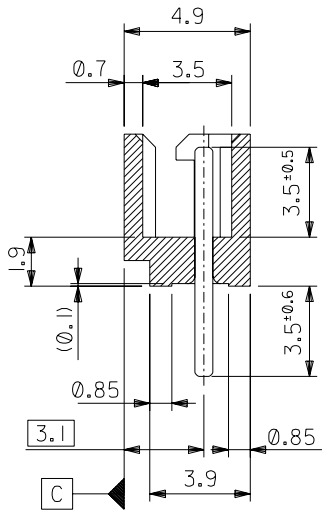
注記
NOTES:

1. 嵌合相手：5264シリーズ
   MATES WITH : 5264 SERIES.

ウエハー：66ナイロン。ガラス入り，UL94V−0
WAFER:66NYLON,GLASS REINFORCED,UL94V-0



ピン：(∅0.7)
PIN:(∅0.7)
黄銅，銅下地錫メッキ
BRASS,TIN OVER
COPPER PLATING



39.9	38.5	35	22-03-5155	5267-15A	15
37.4	36	32.5	-5145	-14A	14
34.9	33.5	30	-5135	-13A	13
32.4	31	27.5	-5125	-12A	12
29.9	28.5	25	-5115	-11A	11
27.4	26	22.5	-5105	-10A	10
24.9	23.5	20	-5095	-09A	9
22.4	21	17.5	-5085	-08A	8
19.9	18.5	15	-5075	-07A	7
17.4	16	12.5	-5065	-06A	6
14.9	13.5	10	-5055	-05A	5
12.4	11	7.5	-5045	-04A	4
9.9	8.5	5	-5035	-03A	3
7.4	6	2.5	22-03-5025	5267-02A	2
C	B	A	EDP NO.	ENG.NO.	極数 NO OF CKT.

角度 ANGLE	±3°					
30以上 OVER	±0.3	B	変更 REVISED	(JC60688)	Y.M	'96/3/26
10以上 OVER 30未満 UNDER	±0.25	A	変更	(J10590)	H.H	'91/7/26
10未満 UNDER	±0.2	0	新規作成	(J80546)	H.H	6/20/88
一般公差 GENERAL TOLERANCES		記号 LTR	変更内容 REVISION RECORD		DR. CHK.	日付 DATE

材料 MATERIAL

仕上げ FINISH

適用電線範囲 WIRE RANGE

被覆外径 INS. RANGE

DRAWN BY 6/20/88 Y.MIZUNO
CHK'D BY '96/03/26 Y.MIZUNO
APP'D BY '96/03/26 M.FUKUSHIMA
尺度 SCALE 5:1

MOLEX-JAPAN CO.,LTD.
日本モレックス株式会社

REVISE ONLY ON CAD SYSTEM

TITLE 名称

2.5 LOW PROFILE
WAFER ASS'Y

DWG. NO. SD-5267-NA

REV B

:MM DIMENSIONS IN METRIC DO NOT SCALE DRAWING

DWG. NO. SD-5267-NA

5267.S30

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